

## N-Channel Enhancement Mode MOSFET

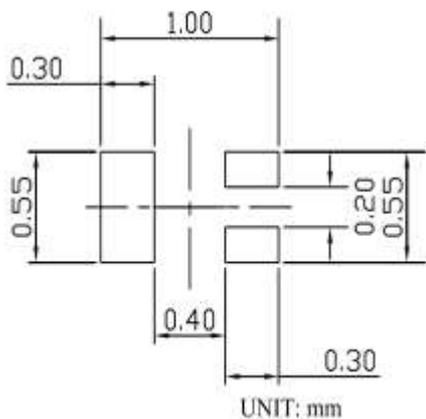
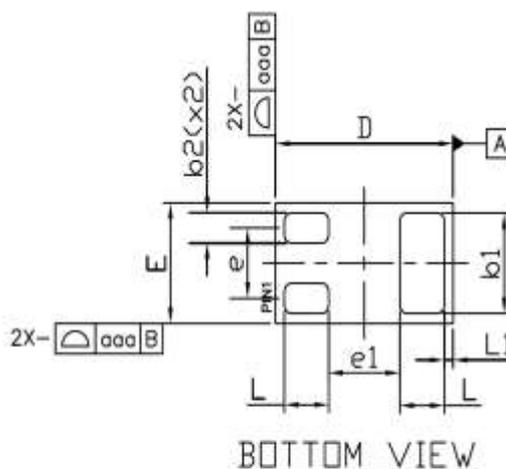
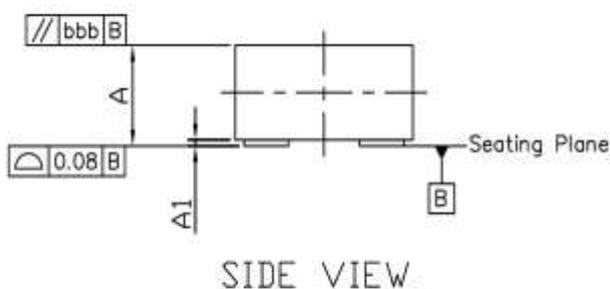
- **Features**

VDS	VGS	RDSon TYP	ID	ESD
20V	±12V	310mR@4V5 490mR@2V5 850mR@1V8	0.7A	1.2K

- **General Description**

This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

- **Package Information**



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.50	0.52	0.55
A1	0.00	0.03	0.05
b1	0.45	0.50	0.55
b2	0.10	0.15	0.20
D	0.95	1.00	1.075
E	0.55	0.60	0.675
e	---	0.35	---
e1	---	0.40	---
L	0.20	0.25	0.30
L1	---	0.05	---
aaa	0.15		
bbb	0.05		

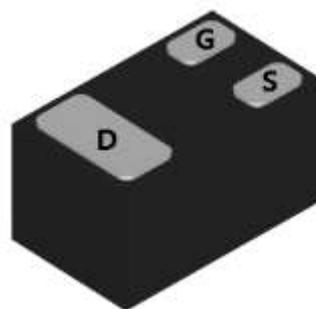
DFN1006

- **Applications**

- Load Switch
- Portable Devices
- DCDC Conversion

- **Pin configuration**

bottom View





# SSC8120GN1

● **Order information**

Device	Package	Marking	Shipping
SSC8120GN1	DFN1006		10000/Tape&Reel

● **Absolute Maximum Ratings** @  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Max	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Continuous Drain Current <sup>a</sup> $V_{GS}@4.5\text{V } T_A = 25^\circ\text{C}$	$I_D$	0.7	A
Continuous Drain Current <sup>a</sup> $V_{GS}@4.5\text{V } T_A = 70^\circ\text{C}$		0.5	A
Plused Drain Current <sup>b</sup>	$I_{DM}$	2.8	A
Power Dissipation <sup>a</sup> $T_C = 25^\circ\text{C}$	$P_D$	0.9	W
Power Dissipation <sup>a</sup> $T_C = 70^\circ\text{C}$		0.5	W
Storage and Junction Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

● **Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 10\text{S}$	83	105	$^\circ\text{C/W}$
	Steady-State	115	143	$^\circ\text{C/W}$
Maximum Junction-to- Ambient <sup>c</sup>	$t \leq 10\text{S}$	201	250	$^\circ\text{C/W}$
	Steady-State	280	340	$^\circ\text{C/W}$

● **Electrical Characteristics** @  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	20	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
Gate-Body Leakage	$I_{GSS}$	$V_{GS} = \pm 12\text{ V}, V_{DS} = 0\text{ V}$	--	--	$\pm 10$	$\mu\text{A}$
<b>ON CHARACTERISTICS<sup>(2)</sup></b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = 50\mu\text{A}$	0.35	0.6	1	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}, I_D = 0.6\text{ A}$	--	310	450	mR



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		$V_{GS} = 2.5\text{ V}, I_D = 0.5\text{ A}$	--	490	765	
		$V_{GS} = 1.8\text{ V}, I_D = 0.35\text{ A}$	--	850	1300	
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	$C_{ISS}$	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	100	--	pF
Output Capacitance	$C_{OSS}$		--	17	--	
Reverse Transfer Capacitance	$C_{RSS}$		--	11	--	
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$T_{D(ON)}$	$V_{DD} = 5\text{ V}, I_D = 0.3\text{ A},$ $V_{GS} = 4.5\text{ V}, R_{GEN} = 6\Omega$	--	--	5	nS
Turn-On Rise Time	$T_R$		--	--	80	
Turn-Off Delay Time	$T_{D(OFF)}$		--	--	26	
Turn-Off Fall Time	$T_F$		--	--	25	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
Diode Forward Voltage <sup>(2)</sup>	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 0.11\text{ A}$	--	0.7	1.3	V

Notes :

a: mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

b: Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2%

c: mounted on FR-4 minimum pad board, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## ● Typical Performance Characteristics

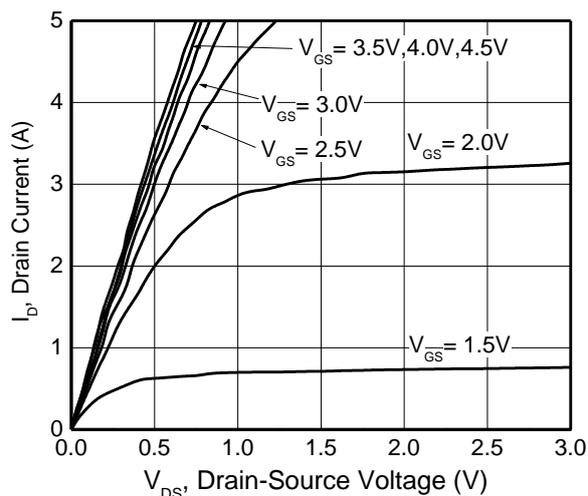


Figure 1. Output Characteristics

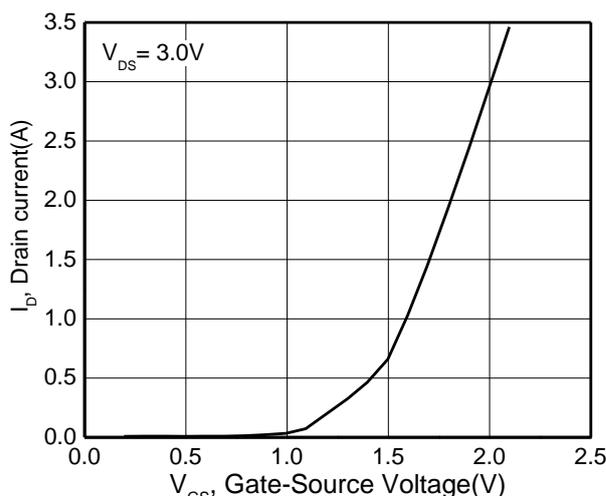
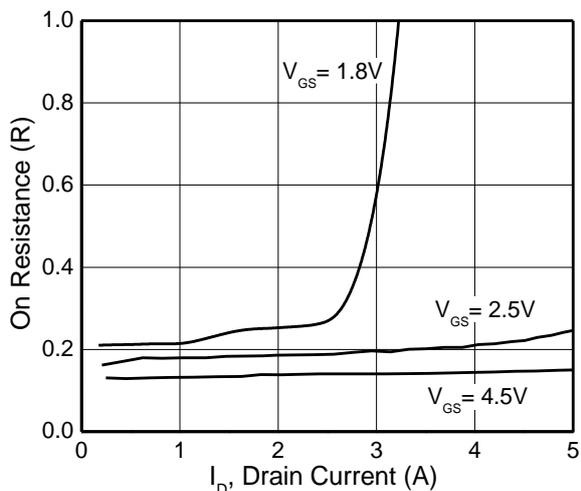
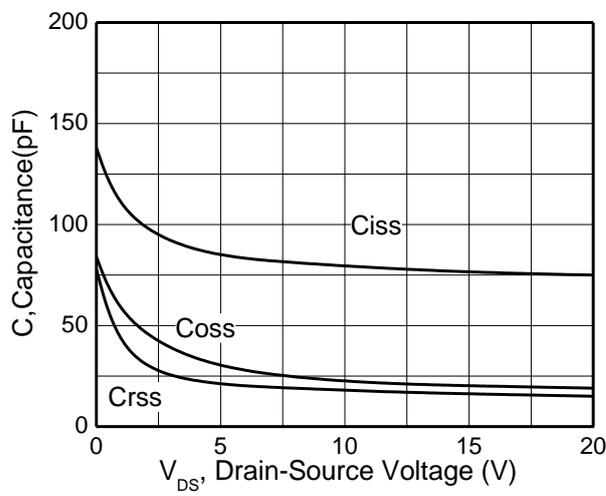


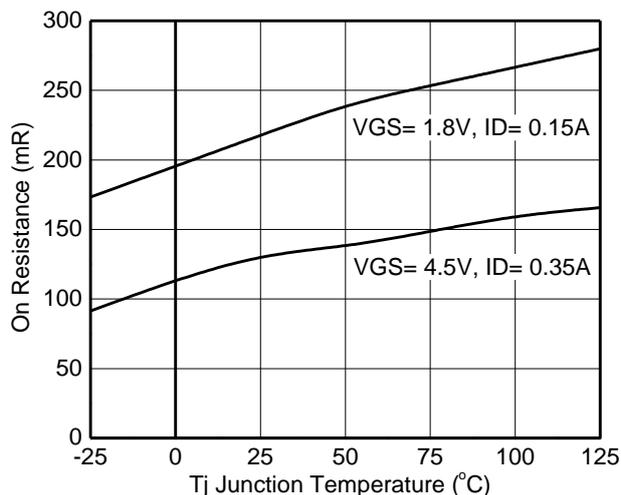
Figure 2. Transfer Characteristics



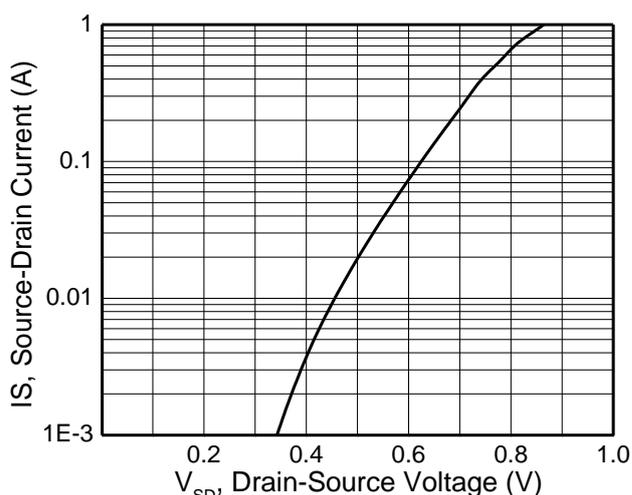
**Figure 3. On Resistance vs. Drain Current**



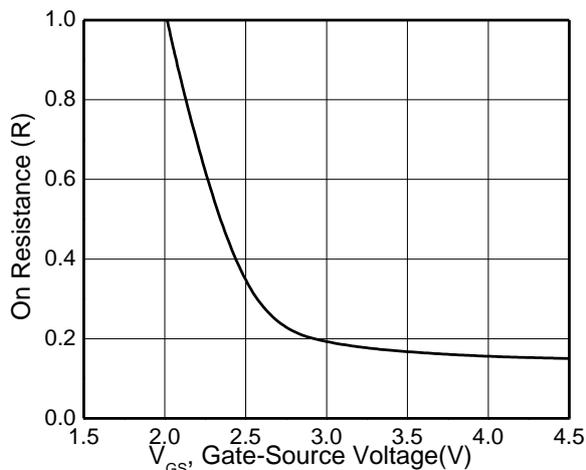
**Figure 4. Capacitance**



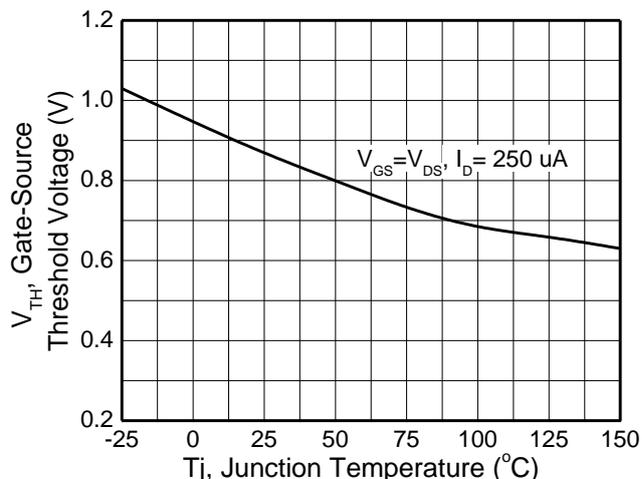
**Figure 5 . On resistance vs. Temperature**



**Figure 6. Diode Forward Characteristics**



**Figure 7. On Resistance vs. Gate-Source Voltage**



**Figure 8. Gate Threshold vs. Temperature**



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